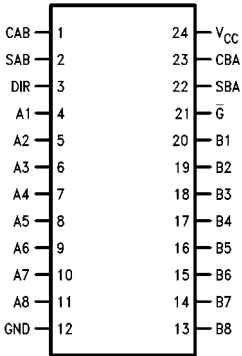


Connection Diagram



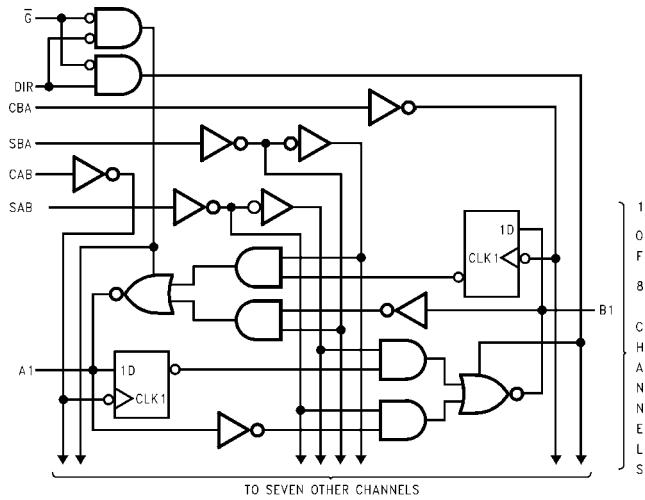
Function Table

Inputs						Data I/O (Note 1)		Operation or Function
$\overline{G}$	DIR	CAB	CBA	SAB	SBA	A1 thru A8	B1 thru B8	
X	X	$\uparrow$	X	X	X	Input	Not Specified	Store A, B Unspecified
X	X	X	$\uparrow$	X	X	Not Specified	Input	Store B, A Unspecified
H	X	$\uparrow$	$\uparrow$	X	X	Input	Input	Store A and B Data
H	X	H/L	H/L	X	X	Input	Input	Isolation, Hold Storage
L	L	X	X	X	L	Output	Input	Real-Time B Data to a Bus
L	L	X	H/L	X	H	Output	Input	Stored B Data to a Bus
L	H	X	X	L	X	Input	Output	Real-Time A Data to B Bus
L	H	H/L	X	H	X	Input	Output	Stored A Data to B Bus

H = HIGH Logic Level
L = LOW Logic Level
X = Don't Care (Either LOW or HIGH Logic Levels including transitions)
H/L = Either LOW or HIGH Logic Level excluding transitions
 $\uparrow$ = Positive going edge of pulse

Note 1: The data output functions may be enabled or disabled by various signals at the $\overline{G}$ and DIR inputs. Data input functions are always enabled, i.e., data at the bus pins will be stored on every LOW-to-HIGH transition on the clock inputs.

Logic Diagram



Absolute Maximum Ratings(Note 2)

Supply Voltage	7V
Input Voltage	
Control Inputs	7V
I/O Ports	5.5V
Operating Free-Air Temperature Range	0°C to +70°C
Storage Temperature Range	–65°C to +150°C
Typical θ_{JA}	
N Package	44.5°C/W
M Package	80.5°C/W

Note 2: The "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the absolute maximum ratings. The "Recommended Operating Conditions" table will define the conditions for actual device operation.

Recommended Operating Conditions

Symbol	Parameter	Min	Nom	Max	Units
V_{CC}	Supply Voltage		5	5.5	V
V_{IH}	HIGH Level Input Voltage				V
V_{IL}	LOW Level Input Voltage			0.8	V
I_{OH}	HIGH Level Output Current			–15	mA
I_{OL}	LOW Level Output Current			24	mA
f_{CLK}	Clock Frequency			40	MHz
t_W	Pulse Duration, Clocks LOW or HIGH				ns
t_{SU}	Data Setup Time, A before CAB or B before CBA (Note 3)	10 $\uparrow$			ns
t_H	Data Hold Time, A after CAB or B after CBA (Note 3)	0 $\uparrow$			ns
T_A	Free Air Operating Temperature			70	°C

Note 3: $\uparrow$ = With reference to the LOW-to-HIGH transition of the respective clock.

Electrical Characteristics

over recommended free air temperature range

Symbol	Parameter	Test Conditions		Min	Typ	Max	Units
V_{IC}	Input Clamp Voltage	$V_{CC} = \text{Min}$, $I_I = -18 \text{ mA}$				–1.2	V
V_{OH}	HIGH Level Output Voltage	$V_{CC} = 4.5\text{V to } 5.5\text{V}$	$I_{OH} = -0.4 \text{ mA}$	$V_{CC} - 2$			V
		$V_{CC} = \text{Min}$	$I_{OH} = -3 \text{ mA}$	2.4	3.2		
			$I_{OH} = \text{Max}$	2			
V_{OL}	LOW Level Output Voltage	$V_{CC} = \text{Min}$	$I_{OL} = 12 \text{ mA}$		0.25	0.4	V
			$I_{OL} = 24 \text{ mA}$		0.35	0.5	
			$I_{OL} = 48 \text{ mA}$		0.35	0.5	
I_I	Input Current at Maximum Input Voltage	$V_{CC} = \text{Max}$	I/O Ports, $V_I = 5.5\text{V}$			100	μA
			Control Inputs, $V_I = 7\text{V}$			100	
I_{IH}	HIGH Level Input Current	$V_{CC} = \text{Max}$, $V_I = 2.7\text{V}$ (Note 4)				20	μA
I_{IL}	LOW Level Input Current	$V_{CC} = \text{Max}$, $V_I = 0.4\text{V}$, (Note 4)	Control Inputs			–200	μA
			I/O Ports			–200	
I_O	Output Drive Current	$V_{CC} = \text{Max}$, $V_O = 2.25\text{V}$		–30		–112	mA
I_{CC}	Supply Current	$V_{CC} = \text{Max}$	Outputs HIGH		47	76	mA
			Outputs LOW		55	88	
			Outputs Disabled		55	88	

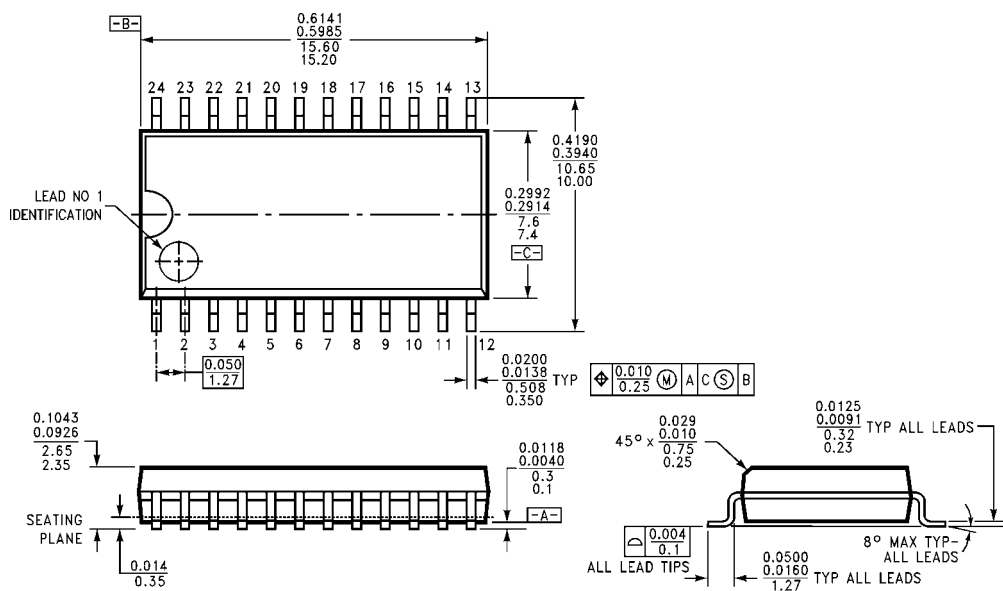
Note 4: For I/O ports the 3-STATE output currents (I_{OZH} and I_{OZL}) are included in the I_{IH} and I_{IL} parameters.

Switching Characteristics

over recommended operating free air temperature range

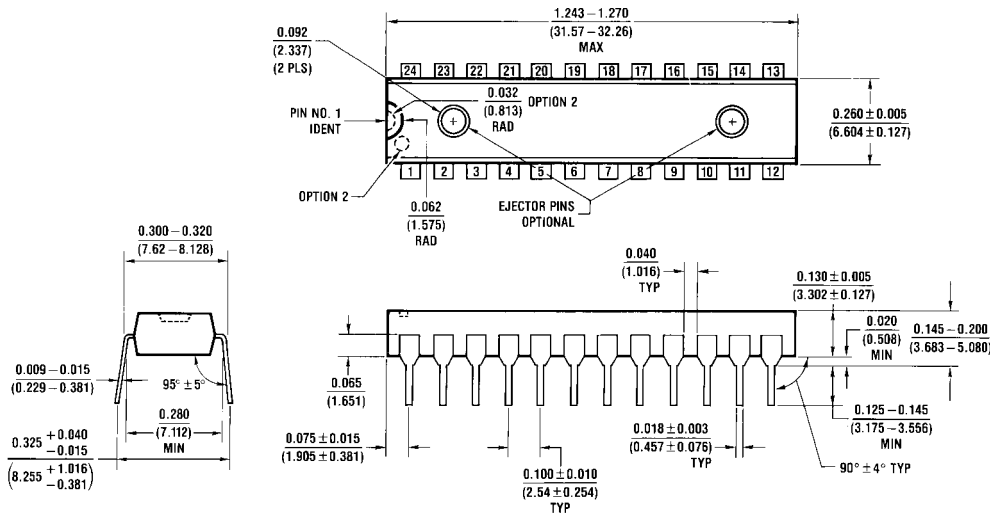
Symbol	Parameter	Conditions	From (Input)	Min	Max	Units
			To (Output)			
t_{PLH}	Propagation Delay Time LOW-to-HIGH Level Output	$V_{CC} = 4.5V$ to $5.5V$, $C_L = 50$ pF, $R_1 = R_2 = 500\Omega$, $T_A = \text{Min to Max}$	CBA or CAB to A or B	10	30	ns
t_{PHL}	Propagation Delay Time HIGH-to-LOW Level Output		CBA or CAB to A or B	5	17	ns
t_{PLH}	Propagation Delay Time LOW-to-HIGH Level Output		A or B to B or A	5	20	ns
t_{PHL}	Propagation Delay Time HIGH-to-LOW Level Output		A or B to B or A	3	12	ns
t_{PLH}	Propagation Delay Time LOW-to-HIGH Level Output (with A or B LOW) (Note 5)		SBA or SAB to A or B	12	35	ns
t_{PHL}	Propagation Delay Time HIGH-to-LOW Level Output (with A or B LOW) (Note 5)		SBA or SAB to A or B	5	20	ns
t_{PLH}	Propagation Delay Time LOW-to-HIGH Level Output (with A or B HIGH) (Note 5)		SBA or SAB to A or B	6	25	ns
t_{PHL}	Propagation Delay Time HIGH-to-LOW Level Output (with A or B HIGH) (Note 5)		SBA or SAB to A or B	5	20	ns
t_{PZH}	Output Enable Time to HIGH Level Output		$\overline{G}$ to A or B	3	17	ns
t_{PZL}	Output Enable Time to LOW Level Output		$\overline{G}$ to A or B	5	20	ns
t_{PHZ}	Output Disable Time from HIGH Level Output		$\overline{G}$ to A or B	1	10	ns
t_{PLZ}	Output Disable Time from LOW Level Output		$\overline{G}$ to A or B	2	16	ns
t_{PZH}	Output Enable Time to HIGH Level Output		DIR to A or B	6	30	ns
t_{PZL}	Output Enable Time to LOW Level Output		DIR to A or B	5	25	ns
t_{PHZ}	Output Disable Time from HIGH Level Output		DIR to A or B	1	10	ns
t_{PLZ}	Output Disable Time from LOW Level Output		DIR to A or B	2	16	ns

Note 5: These parameters are measured with the internal output state of the storage register opposite to that of the bus input.



**24-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
Package Number M24B**

inches (millimeters) unless otherwise noted (Continued)



**24-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide
Package Number N24C**

N24C (REV F)

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